Yuk Shing Circuits Co. Ltd.

COMPANY PROFILE



Yuk Shing Circuits was incorporated in 1979 and started producing single-sided PCBs for consumer electronic products in Hong Kong. In 1993, we moved our production facilities to Dongguan. Since then, we have been producing high-quality PCBs which are utilized in various sectors such as video entertainment systems, micro-motors, telecommunications, computer peripherals and automotive.

At Yuk Shing Circuits, our philosophy emphasizes on the importance of quality, dependability and on-time delivery in today's highly competitive market. Our staff of over 200 is well-trained and familiar with every phase of PCB manufacturing process, which is strictly controlled by our registered ISO9001:2015 & IATF16949:2016 quality management systems. We have advanced automated manufacturing facilities and quality assurance equipment to accommodate the demand of high precision PCBs. Still we believe that the key ingredient in producing high quality PCBs is experience, and we do have the best.

Besides enforcing our policy on quality, it is our objective to be environmentally conscious. Our products comply with EU's RoHS Directive. We also have been adapting management regulations for controlled substances such as Sony's SS-00259 & ISO14001:2015 to deepen our commitment and responsibility to the environment.

Yuk Shing Circuits wants to become your PCB partner. We value every partnership by understanding your needs, and we reassure you that we will synchronize with your method of conducting business. We sincerely invite you to experience the difference with us. Exceeding your expectation is our ultimate goal.

玉成電路有限公司于1979年在香港成立，初期生产一般消费电子产品所需的单面电路板为主，及后于1993年把生产线迁移到东莞市厚街镇，开始主力生产应用于高端音响/摄影器材、微形马达、通信设备，计算机周边设备及汽车工业等各方面高端电路板。

多年来，玉成经营理念均注重『产品质量、合理价钱、交期准确和忠诚服务』，并凭此立足于竞争激烈市场。我们所拥有之200多名员工均是训练有素和熟悉每一道生产流程及严格按照『ISO9001:2015 及 IATF16949:2016』要求来执行质量管理体系运作。我们购置有先进生产设备，精密检测和质监仪器，再加上优良而成熟生产技术及丰富行业经验，满足市场对高端电路板所需。

强调质量的同时，亦必须具备环境保护意识。玉成所有产品均符合欧盟『有害物质限制指令(RoHS)』及索尼『SS-00259 环境有害物质管理』规定，并按照有关要求作出严格管理；同时获得ISO14001:2015认证，深化对环境责任的承诺。

玉成十分珍惜与每一个客户的关系，并竭力去了解和满足客户要求，我们承诺，除经营方向与您的业务一致外，超出您的期望更是我们终极目标。诚意邀请您与我们一起分享不一样的经验，继而让玉成作为您长久的合作伙伴。



『玉成電路有限公司』は1979年に香港で設立されました。最初は家電製品の片面回路基板を製造しまして、そのあと、1993年から生産ラインを東莞市の厚街町に移転しました。それと共に、専ら、高級なオーディオ、撮影機材、マイクロモーター、通信機器、コンピュータの様々な周辺機器、又、自動車用の先端な回路基板の製造を開始しました。

『玉成』のビジネス哲学は、「製品の品質、合理的な価格、時間通りの配送と誠実で信用がおけるサービス」を重んじておるということでございます。ここ数年　それに頼って、現在その競争が激しい市場に立脚地を獲得することができました。弊社には、訓練に訓練を重ねて、すべての生産プロセスをよくしっている従業員が200人以上も居ります。「ISO9001：2015およびIATF16949：2016」の認証要件に基づいて、厳格に品質システムを管理しております。我々は、進んでいる生産設備、精密なテストと品質保証の装置を備えております。それに、洗練されたテクノロジ及び幅広い業界経験を持っています。それで、市場が回路基板への高い要求を満たすことになりました。

『玉成』は、品質を重視している同時、環境意識にも極めて関心を払っています。すべての製品も、欧州連合（EU）の有害物質制限の指令（RoHS）とソニーの『SS-00259有害物質管理』の要件に叶っております。関連する要件に従って、厳格な管理を行って、そして、『ISO14001:2015』の認証を取得しました。

『玉成』は、お客様との関係を大切にして、また、顧客の要件を理解して、満たそうと尽力しています。お客様の経営方針と一致になると承諾するだけではなく、お客様の期待を超えることが私たちの最終目標です。『玉成』は、誠意を持って、お客様と一緒に様々な経験を分かち合って、また、貴社の提携パートナーになってほしいと望んでおります!

东莞玉成电路板有限公司

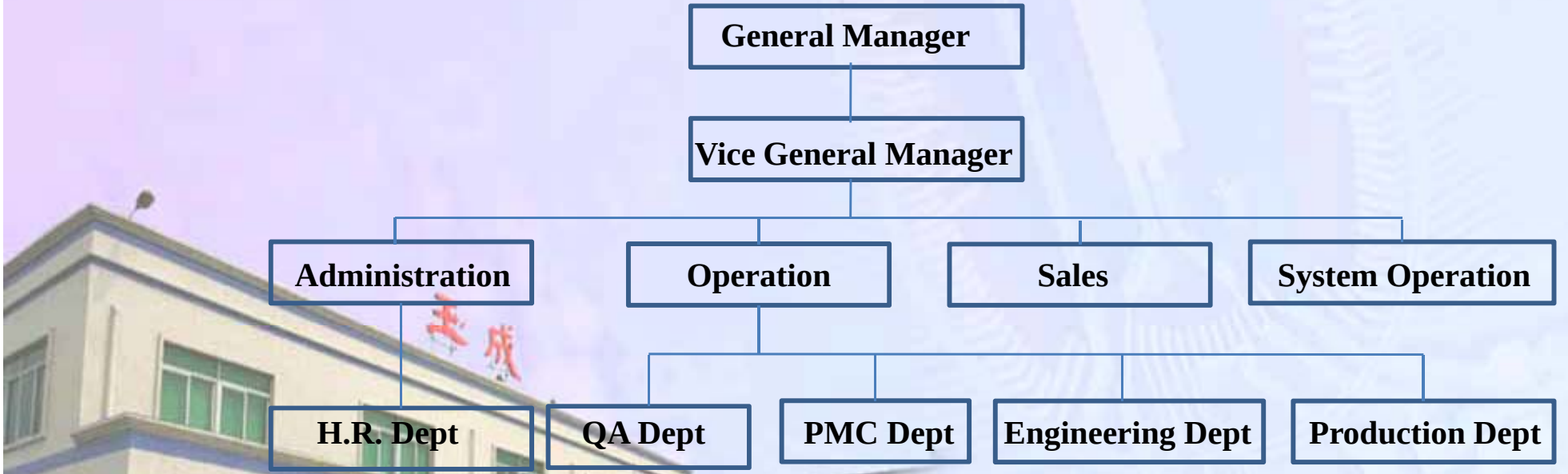
Dongguan Yuk Shing PCB Company Limited

General Information

Established Date	**September 1979**
Revenues 2023	**80Million HKD (11 Million USD)**
Investment	**10 Million HKD**
Land Area	**92,000 sq. ft. (8,300 sq. m.)**
Office Area	**5,000 sq. ft. (450 sq. m.)**
Manufacturing Area	**50,000 sq. ft. (4,500 sq. m.)**
Clean Area (Class 100K)	**4,500 sq. ft. (400 sq. m.)**
Output Capability per Month	**400,000 sq. ft. (40,000 sq. m.)**
Operation Hours per Month	**200 - 300 Hours**
Quality Management	**ISO 9001:2015 & IATF16949:2016**
Environment Management	**ISO14001:2015**
No. of Employees	
Administration	**5**
Office Staffs	**25**
Production	**140**
Quality Assurance & Engineering	**20**
Office Address	**Room 2, Block D, 3rd Floor, Tuen Mun Industrial Center, TMTL 76, Pui To Road, Tuen Mun, N. T. Hong Kong.**
Factory Address	**Gu Keng Industrial Park, Xintang, Houjie, Dongguan, Guangdong, China.**
Website	**http://www.yukshingpcb.com**

东莞玉成电路板有限公司
Dongguan Yuk Shing PCB Company Limited

Organization Chart



东莞玉成电路板有限公司

Dongguan Yuk Shing PCB Company Limited

Major Customers

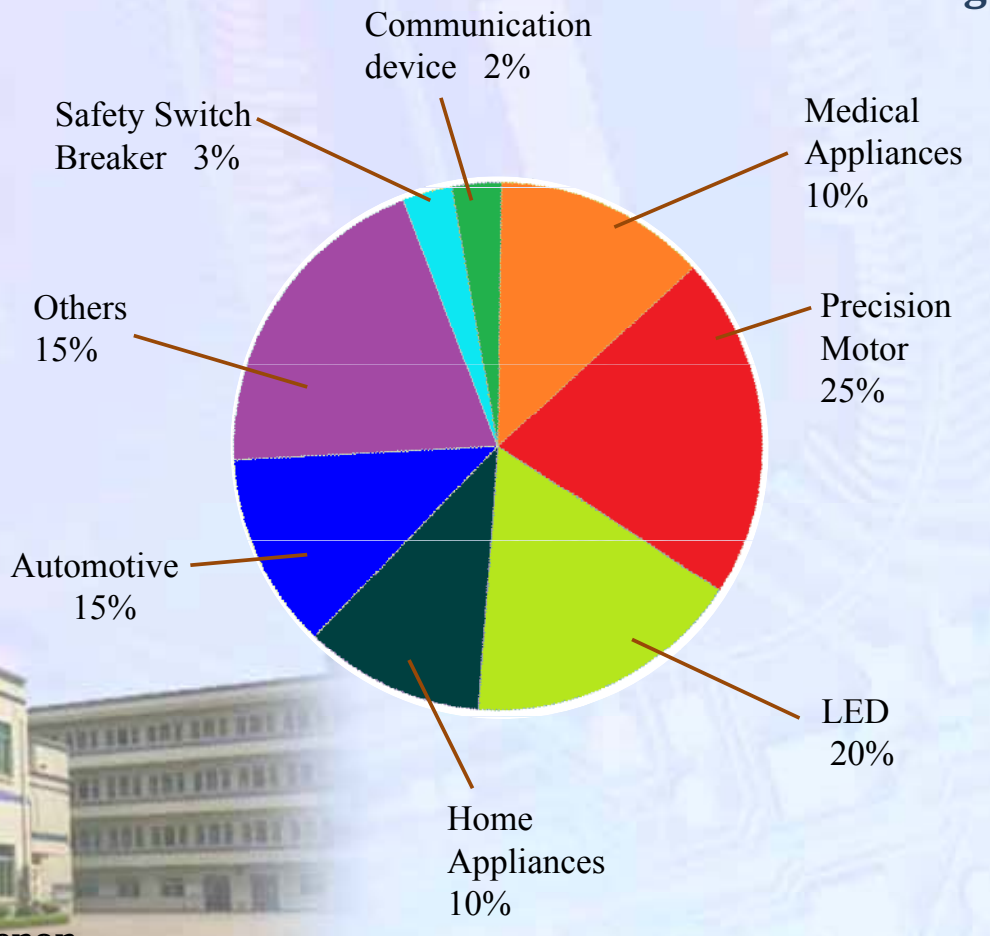
1) **Panasonic**
2) **HP**
3) **Sony**
4) **Denon**
5) **Defond**
6) **Johnson Electric**
7) **Philips**
8) **Dextra**

Market distribution:

Japan:50%;
Europe&America: 20%
Southeast Asia: 10%
China &Others: 20%

Main Japanese customers:
Sony ; Panasonice ; Shinano;
Mabuchi;Minembea;Nippon Keki;Denon

Product Categories



东莞玉成电路板有限公司

Dongguan Yuk Shing PCB Company Limited

Manufacturing Process Flow



Imaging



Etching



Printing



Punching



O/S testing



Packing & Delivery



Machineries and Equipment — No. of Sets

Shearing Machine(开料机)	3
Silk Screen Printer(丝印机)	8
Automatic Silk Screen Printer(自动丝印机)	2
Liquid Photo-Imageable Resist Coater(涂布机)	2
Exposure Units for LPI Resist(曝光机)	6
LPI Resists Developing Unit(显影机)	4
Scrubbing Machine(磨板机)	2
Copper Surface Micro-Etching System(微蚀机)	2
Copper Etching System(蚀刻机)	2
Conveyorized UV Curing System(UV干燥机)	2
Air-circulated Oven (恒温炉)	8
Automatic Guide Hole Drilling Machine(自动打孔机)	6
Punching Press with Fine Piercing System (液压冲床)	5
Automatic Punching Press (自动冲床)	3
Electrical Open-Short Circuit Tester (开短路测试机)	4
Automatic Electrical Open-Short Circuit Tester (自动开短路测试机)	4
Hi-Pot Tester （高压测试仪）	1
Flying Probe Tester 飞针测试机	1
Missing holes checking Machine(自动通孔机）	1
CNC V-Cut Machine （ 数控V坑机)	2
Organic Solderability Preservative Coating System (抗氧化机)	1
CNC Drill / Router Machine （数控钻铣机)	3



Quality assurance Instruments

Stereo Microscope with Camera(显微镜), Pin Gauges针规, Calipers(卡尺), UV Intensity Detector(紫外线强度检测仪) , Tensioning Meter(张力计), Mini-soldering Pot(小型浸锡机), Ink Thickness Gauge(油墨厚度测试仪), Cross Hatch Cutter(十字划割器), Micro Cross-section Lab(微型切版机) , Automatic XYZCMM(三次元自动视觉测量仪), Chemical Analysis Lab(化学分析实验室), Copper Thickness Checker(铜厚测试仪), Wire Bonder and Bonding Force Tester(邦定拉力测试仪)etc.

Capabilities & Parameters

Laminates (板材)

ANSI Grade (美国国家标准协会等级)	XPC, FR-1, FR-2, CEM-1, CEM-3, FR-4, Metal Base
Thickness (厚度) (mm)	0.8 - 1.6 for Phenolic Paper(酚醛树脂); 0.1 - 2.5 for Epoxy Glass (玻璃布)
Flame Class(防火等级)(UL94)	HB, V-0
Comparative Tracking Index(相对漏电起痕指数)(UL746A)	100 Volts - 600 Volts +
Direct Support (UL796) (符合(UL796)要求板材)	Yes
Maximum Operating Temperature (最高操作温度)	105° C, 130° C
Halogen Free (Green) Laminates (无卤板材)	Available (可提供)

Circuitry Pattern(线路)

Copper Weight (铜重)	17 – 105 µm (½ oz. to 3 oz.) (½ 安士 至 3 安士)

Copper Trace - Silk Screen Printed (丝印线路)

Line Width / Spacing for ½ & 1 oz. Copper 线宽\线距 (½ 安士 至 1 安士)	min.(最小) 0.20 mm (8 mil)
Line Width / Spacing for 2 oz. & up Copper 线宽\线距 (2 安士 或以上)	min. (最小) 0.25 mm (10 mil)

Copper Trace - Photo-Imaged (感光线路-湿膜)

Line Width / Spacing for ½ oz. Copper 线宽\线距 (½ 安士)	min. (最小) 0.10 mm (4 mil)
Line Width / Spacing for 1 oz. Copper 线宽\线距 (1 安士)	min. (最小) 0.12 mm (5 mil)
Line Width / Spacing for 2 oz. & up Copper 线宽\线距 (2 安士 或以上)	min. (最小) 0.18 mm (7 mil)

SMD Copper Pad Dimension (焊盘尺寸) min. (最小) 0.8 mm X 1.0 mm

Offset between Cu Pad and Mechanical Datum(偏移) max. (最大)0.05 mm per 100 mm linear

Solder Mask (防焊)

Available Colors (可选择颜色)	Green, Blue, Black, Red, White (绿,蓝,黑,红,白)
Clearance between Copper Pad and Solder Mask Opening (焊盘与防焊间隙)	
Silk Screen Printed (UV and Thermal Cure) (丝印UV 固化)	
- for 17 µm Copper (铜 厚 17 µm)	min.(最小) 0.20 mm
- for 35 µm Copper (铜 厚 35 µm)	min.(最小) 0.20 mm
- for 70 µm Copper (铜 厚 70 µm)	min.(最小) 0.30 mm
Liquid Photo-Imageable (液态感光)	
- for 17 / 35 µm Copper (铜 厚 17/35 µm)	min.(最小) 0.15 mm
- for 70 µm Copper (铜 厚 70 µm)	min.(最小) 0.20 mm
Offset between Copper Pad and Solder Mask Opening (焊盘与防焊偏移距)	
Silk Screen Printed (丝印)	max.(最大) 0.15 mm
Liquid Photo-Imageable (液态感光)	max.(最大) 0.10 mm
Peelable Solder Resist – Blue (可剥阻焊—蓝胶)	0.10 - 0.40 mm in Thickness (厚度)

Legend (字符)

Silk Screen Printed (丝印)	Available Colors: Green, Blue, Black, White, Yellow (可选择颜色:绿,蓝,黑,白,黄)
Min. Printable Character Size.(最小印刷尺寸)	1.0 mm x 1.2 mm
Liquid Photo-Imageable (液态感光)	Available upon Request (可提供)

Surface Finishes (表面后处理)

Nickel Plate 电镍	3.0 – 8.0 µm
Gold Plate 电金	0.025 – 0.5 µm gold thickness (金厚)
Electroless Nickel Immersion Gold (ENIG) (沉镍金)	0.05 - 0.1 µm gold thickness (金厚)
Hot Air Leveling (Lead Free or Tin-Lead) (喷锡:无铅/有铅)	3 – 10+ µm
Silk Screen Printed Carbon Key / Jumper (碳油)	Made to Specification (按要求制造)
Immersion Tin (沉锡)	0.5 – 1.0 µm
OSP (MEC) (水溶预焊剂)	≥ 0.5 Abs.

Profiling (外形加工)

Minimum Punched Hole Diameter (最小孔径-冲孔)	≥0.5 T (T=Board Thickness) (T=板厚)
Minimum Distance between Two Adjacent Punched Holes (两孔之间最小距离)	≥ T
Distance between Holes to Board Edge (孔与板边距离)	
Phenolic Paper & CEM-1 / -3 (Hole Punched)(酚醛树脂 / CEM-1 / CEM-3 -冲孔)	0.75 mm
Epoxy Glass (T= 0.2 - 1.0 mm, Hole Drilled)(玻璃布 (T= 0.2 - 1.0 mm,钻孔)	0.85 mm
Epoxy Glass (T= 1.2 mm & Up, Hole Drilled)(玻璃布(T= 1.2 以上,钻孔)	0.95 mm
Largest PCB Array Size (最大可冲外形尺寸 - 每块板)	500 mm x 560 mm
Max. No. of Holes per Punch Tooling (Approx.)(最多冲孔数量- 每冲次)	
Paper Phenolic 酚醛树脂	2000 (based on Ø1.0 mm) (基于孔径为 Ø1.0 mm)
CEM-1 / CEM-3 玻璃布	1200 (based on Ø1.0 mm) (基于孔径为 Ø1.0 mm)
Minimum Space between Two Adjacent PCBs on a Panel (两电路板之间最小间距-每块板)	
V-Cut Type (V 坑)	0.2 mm
Push Back Type (反压式)	6.0 mm
Breakaway Type (拗板孔)	1.2 mm
Tooling (模具)	
Lead-time 制造需时	About 2 weeks (约 2 周)
Life Time 模具寿命	
For material 板材 CEM-1、CEM-3、FR-4	About100,000 hits (约 100,000 冲次)
For material 板材 XPC 、FR-1 、FR-2	About 150,000 hits (约 150,000 冲次)

Electrical Performance (电气性能)

Maximum Test Isolated Resistance for CEM or FR-4 最大绝缘电阻（CEM 或 FR-4）	100 MΩ at 250V
Minimum Test Continuity Resistance 最小绝缘电阻	10 Ohms
Maximum No. of Test Points per Panel 最大测试点数(每块板)	4096

Product Types（产品种类）

Single Sided PCB (单面电路板)

Double Sided and Multilayer PCB (双面及多层电路板)

Characteristic (特性)

Carbon Jumper PCB（碳油电路板）

Push Back Type PCB (Min. Thk. : 0.3 mm Epoxy Glass)(反压电路板最少厚度: 0.3mm FR-4)

Nickel Gold Plating & Immersion Nickel Gold PCB (电/沉镍金电路板)

Lead Free HAL PCB（无铅喷锡电路板）

Thin PCB (UL Recognized Thickness : 0.1 mm) 纤薄电路板(完成板厚为 0.1mm)

Fine Line Width / Spacing PCB (4 / 4 mil for 1 oz. Cu)
精密电路板　线宽\线距 (0.1mm/0.1mm - 1安士铜)



Most Used Laminates (常規板材)

ANSI	FR-1	FR-2	CEM-1	CEM-3	FR-4	Aluminum Base
Thickness / Mfr	0.8-1.6mm	0.8-1.6mm	0.8-1.6mm	0.5-1.6mm	0.1-2.5mm	0.2-2.5mm
Chang Chun	CCP-3400 CCP-6400(HF)	CCP-7400	CCP-508 CCP-518(HF/CTI≧600)			
Kingboard	KB-3151C KB-3152(HF)	KB-2150	KB-5150		KB-6160	
Panasonic	R-8500(HF/CTI≧600) R-8700(CTI≧600)			R-1781	R-1566(HF)	
Shengyi			S3110	S2155(HF) S2600(CTI≧600) S2130	S1170(Tg170) S1141 S1155(HF) S1600(CTI≧600)	
Eternal	ETL-XPC-240T ETL-XPC-207(HF)					
Nan Ya			CEM-1-05(HF)		NP-140	
Jin Bao	ZD-90F		ZD-95(G)F			
Chin-Shi						CS-AL-88/89
HuaZheng						HA80



东莞玉成电路板有限公司

Dongguan Yuk Shing PCB Company Limited

Approval & Certification

Type	Certifying agencies	Certificate number	Issue date
UL/ULC	Underwriters Lab.	E-74210	1980
ISO9001	BSI	FM60195	2001-11-26
IATF16949	BSI	569185	2011-03-24
ISO14001	BSI	EMS606506	2014-04-21
RoHS	Compliance Report Available upon Request		



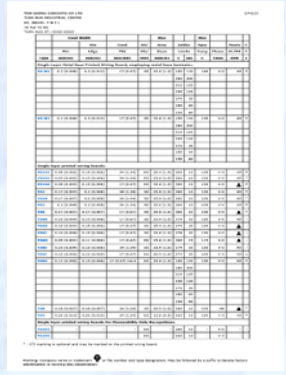
ISO 9001:2015



IATF16949:2016



ISO 14001:2015


UL Yellow Card

Quality Acceptance Criteria

Acceptability of Printed Boards IPC-A-600K Level 1&2

OQC Sampling Inspection Plan

ANSI/ASQC Z1.4 Level II (0.65)
Automotive C=0 AQL 0.65